



Leaded solder paste

LEAD FREE SOLDER

FC63-BZ(L) Standard type

Reducing solder balls, enabling stable printing. Also contributing to reduction in waste solder paste.

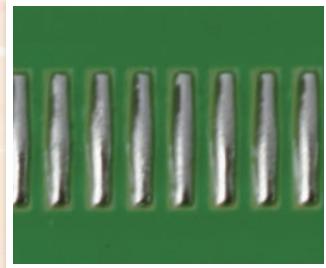
Fine Solder



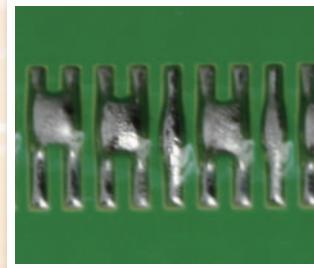
Product Features

■ Significant reduction in solder balls

Our unique flux technology enables the reduction of solder balls by controlling slump (solder outflow beneath components or off the land) during pre-heating.



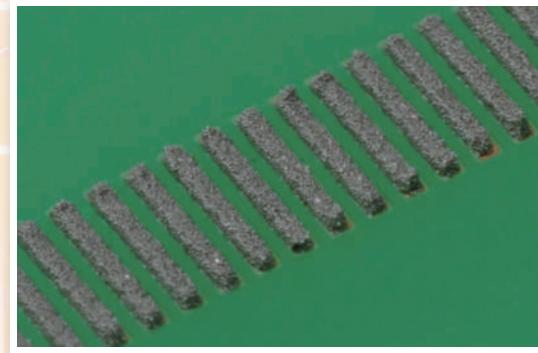
Φ MATSUO
FC63-BZ(L)



• Equivalent products from other manufacturers. •

■ Excellent printing stability

Using an activation agent with substantial stability at room temperatures ensures stable rolling performance in long hours of printing operation, contributing to reduction in wasted solder paste.



• QFP •

Items	FC63-BZ(L)	Test method
Alloy composition	Sn63%-Pb37%	JIS Z3282
Solidus temperature	Approx. 183°C	JIS Z3282
Liquidus temperature	Approx. 183°C	JIS Z3282
Particle size	20~38μm (Type4)	JIS Z3284(J-STD-005)
Flux content	10.2%	JIS Z3197
Halide content	0.05%	JIS Z3197
Viscosity	190Pa·s	JIS Z3284
Thixotropy index	0.56	JIS Z3284
Copper plate corrosion test	Pass	JIS Z3197
Insulation resistance test (85°C 85%RH 168hr)	> 5.0×10 ⁸ Ω	JIS Z3197
Migration test (85°C 85%RH 1,000hr)	Pass	JIS Z3197
Spread rate	96%	JIS Z3197



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Content may be changed without notice.

